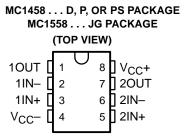
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- Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Designed to Be Interchangeable With Motorola MC1558/MC1458 and Signetics S5558/N5558

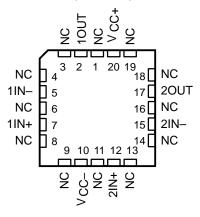
description/ordering information

The MC1458 and MC1558 are dual general-purpose operational amplifiers, with each half electrically similar to the μ A741, except that offset null capability is not provided.

The high-common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.



MC1558...FK PACKAGE (TOP VIEW)



NC - No internal connection

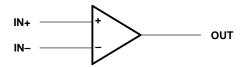
ORDERING INFORMATION

TA	V _{IO} max AT 25°C	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE Marking	
		PDIP (P)	Tube	MC1458P	MC1458P	
0°C to 70°C	6 mV	SOIC (D)	Tube	MC1458D	MC1458	
0 0 10 70 0	OIIIV	3010 (D)	Tape and reel	MC1458DR	IVIC 1436	
		SOP (PS)	Tape and reel	MC1458PSR	M1458	
		CDIP (JG)	Tube	MC1558JG	MC1558JG	
−55°C to 125°C	5 mV	CDIP (JGB)	Tube	MC1558JGB	MC1558JGB	
		LCCC (FK)	Tube	MC1558FK	MC1558FK	

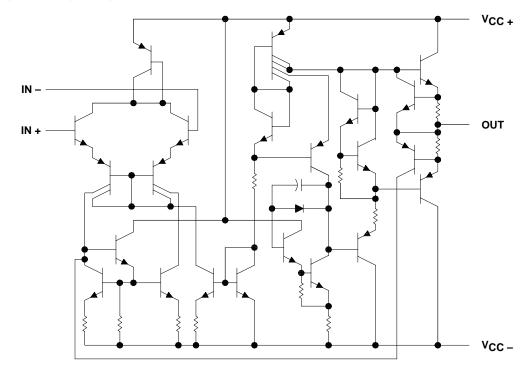
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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symbol (each amplifier)



schematic (each amplifier)





MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC+} (see Note 1):	MC1458		
Supply voltage, V _{CC} (see Note 1):	MC1458		–18 V
	MC1558		–22 V
Differential input voltage, V _{ID} (see N	lote 2)		±30 V
Input voltage, V _I (either input, see N	otes 1 and 3)		±15 V
Duration of output short circuit (see	Note 4)		Unlimited
Operating virtual junction temperatu	re, T _J		150°C
Package thermal impedance, θ_{JA} (s	ee Notes 5 and 6):	D package	97°C/W
		P package	85°C/W
		PS package	95°C/W
Package thermal impedance, θ_{JC} (s	ee Notes 7 and 8):	FK package	5.61°C/W
		JG package	14.5°C/W
Case temperature for 60 seconds: F	K package		260°C
Lead temperature 1,6 mm (1/16 inch	n) from case for 10	seconds: JG package	300°C
Lead temperature 1,6 mm (1/16 inch	n) from case for 60	seconds: D, P, or PS package	260°C
Storage temperature range, T _{stg}			–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - 4. The output can be shorted to ground or either power supply. For the MC1558 only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 70°C free-air temperature.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

			MIN	MAX	UNIT
V _{CC±}	Supply voltage		±5	±15	V
ТД	Operating free air temperature range	MC1458	0	70	°C
I 'A	Operating free-air temperature range		-55	125	J



MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

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electrical characteristics at specified free-air temperature, $V_{\text{CC}\pm}$ = $\pm 15~\text{V}$

PARAMETER			001101710110	.+	N	/IC1458		MC1558		UNIT	
	IANAMETEN		TEST CONDITIONST			TYP	MAX	MIN	TYP	MAX	UNII
VIO	Input offset voltage	V _O = 0		25°C		1	6		1	5	mV
۷IO	input onset voltage			Full range			7.5			6	1111
li o	Input offset current	V _O = 0		25°C		20	200		20	200	nA
IO	input onset current	ΛO = 0		Full range			300			500	ПА
I _{IB}	Input bias current	V _O = 0		25°C		80	500		80	500	nA
ıВ	input bias current	VO = V		Full range			800			1500	11/3
V _{ICR}	Common-mode input			25°C	±12	±13		±12	±13		V
*ICR	voltage range			Full range	±12			±12			v
		$R_L = 10 \text{ k}\Omega$		25°C	±12	±14		±12	±14		
Vом	Maximum peak output	R _L ≥ 10 kΩ		Full range	±12			±12			V
VOM	voltage swing	$R_L = 2 k\Omega$		25°C	±10	±13		±10	±13		v
		$R_L \ge 2 k\Omega$		Full range	±10			±10			
۸. ۱۰	Large-signal differential	P. > 2 kO	V _O = ±10 V	25°C	20	200		50	200		V/mV
AVD	voltage amplification	$R_L \ge 2 k\Omega$, \		Full range	15			25			
ВОМ	Maximum-output-swing bandwidth (closed loop)	$\begin{aligned} R_L &= 2 \ k \Omega, & V_O \geq \pm 10 \ V, \\ A_{VD} &= 1, & THD \geq 5\% \end{aligned}$		25°C		14			14		kHz
B ₁	Unity-gain bandwidth			25°C		1			1		MHz
φm	Phase margin	A _{VD} = 1		25°C		65			65		deg
·	Gain margin			25°C		11			11		dB
r _i	Input resistance			25°C	0.3	2		0.3*	2		МΩ
r _o	Output resistance	V _O = 0,	See Note 9	25°C		75			75		Ω
C _i	Input capacitance			25°C		1.4			1.4		pF
z _{ic}	Common-mode input impedance	f = 20 Hz		25°C		200			200		МΩ
CMDD	Common-mode	V _{IC} = V _{ICR} min,		25°C	70	90		70	90		10
CMRR	rejection ratio	V _O = 0		Full range	70			70			dB
ksvs	Supply-voltage sensitivity	$V_{CC} = \pm 9 \text{ V to}$	±15 V,	25°C		30	150		30	150	μV/V
	$(\Delta V_{IO}/\Delta V_{CC})$	VO = 0		Full range			150			150	
Vn	Equivalent input noise voltage (closed loop)	A _{VD} = 100, f = 1 kHz,	R _S = 0, BW = 1 Hz	25°C		45			45		nV/√Hz
IOS	Short-circuit output current			25°C		±25	±40		±25	±40	mA
	Supply current	V _O = 0, No load		25°C		3.4	5.6		3.4	5	mA
ICC	(both amplifiers)			Full range			6.6			6.6	
D-	Total power dissipation	V- 0 N-1		25°C		100	170		100	150	\^/
P_{D}	(both amplifiers)	$V_O = 0$, No load		Full range		-	200			200	mW
V _{O1} /V _{O2}	Crosstalk attenuation			25°C		120			120		dB

^{*}On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All characteristics are specified under open-loop operating conditions with zero common-mode input voltage, unless otherwise specified. Full range for MC1458 is 0°C to 70°C and for MC1558 is -55°C to 125°C.

NOTE 9: This typical value applies only at frequencies above a few hundred hertz because of the effect of drift and thermal feedback.

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operating characteristics, $V_{CC\pm}$ = ± 15 V, C_L = 100 pF, T_A = 25°C (see Figure 1)

PARAMETER		TEST COA	MC1458			MC1558			UNIT	
		1231 CON	TEST CONDITIONS			MAX	MIN	TYP	MAX	ONIT
Ţ.	Rise time	$V_{I} = 20 \text{ mV},$	$R_L = 2 k\Omega$,		0.3			0.3		μs
۱۲	Overshoot factor	V _I = 20 mV,	$R_L = 2 k\Omega$		5			5		%
SR	Slew rate at unity gain	V _I = 10 V,	$R_L = 2 k\Omega$		0.5			0.5		V/μs

PARAMETER MEASUREMENT INFORMATION

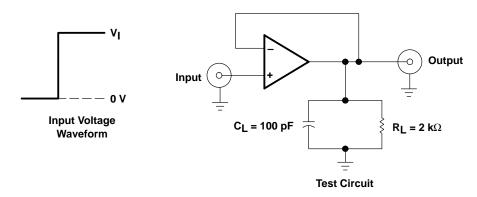


Figure 1. Rise-Time, Overshoot, and Slew-Rate Waveform and Test Circuit





i.com 31-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
5962-9760301Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	Level-NC-NC-NC
5962-9760301QPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	Level-NC-NC-NC
MC1458D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
MC1458DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
MC1458P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
MC1458PSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
MC1558FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	Level-NC-NC-NC
MC1558JG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	Level-NC-NC-NC
MC1558JGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	Level-NC-NC-NC
MC1558P	OBSOLETE	PDIP	Р	8	•	TBD	Call TI	Call TI
SN98212P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

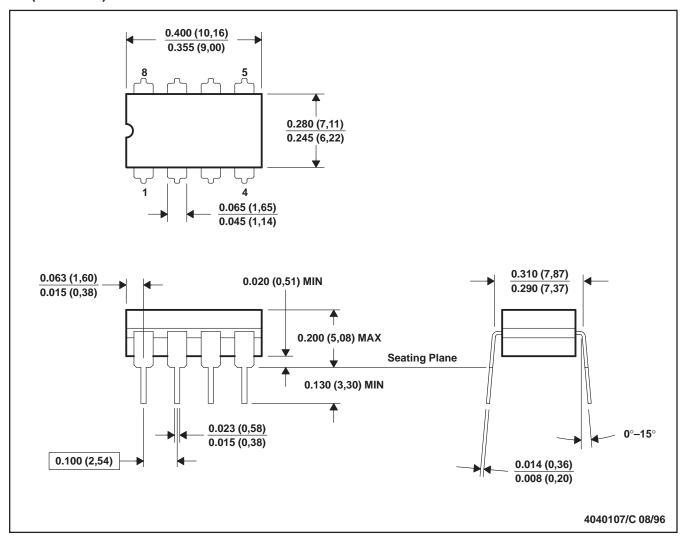
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



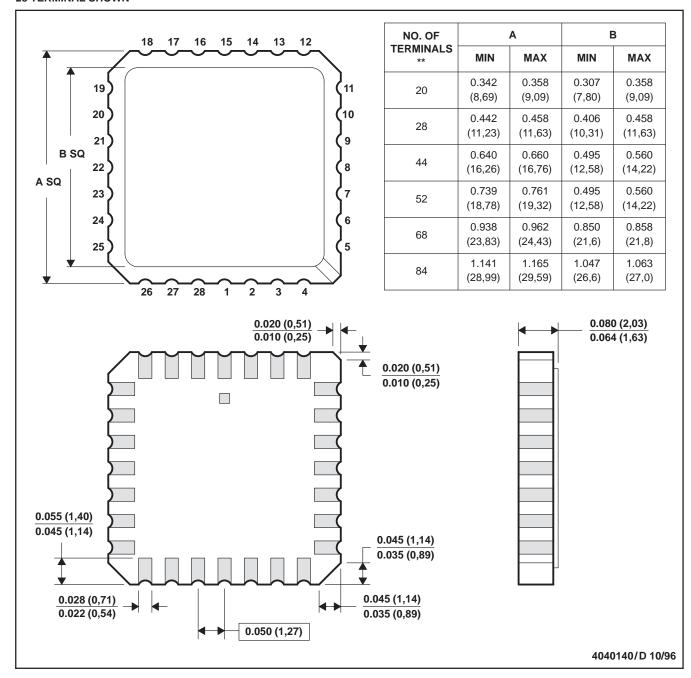
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



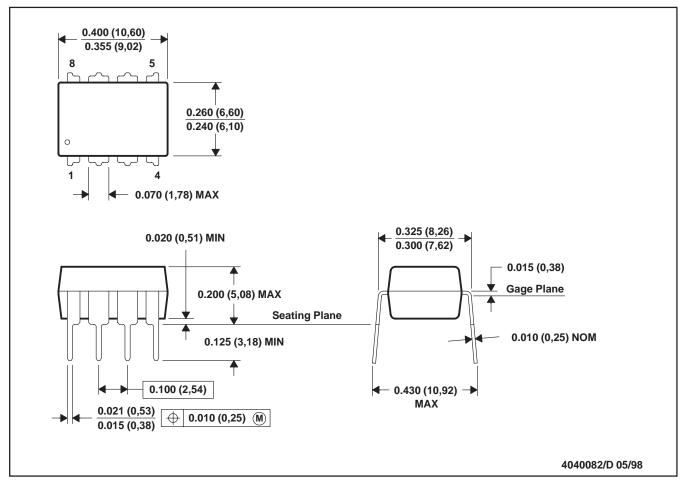
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



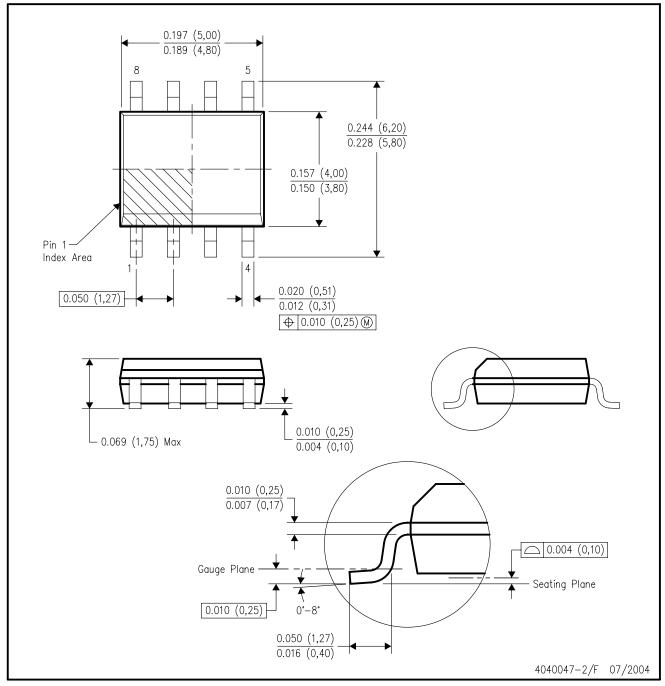
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

D (R-PDSO-G8)

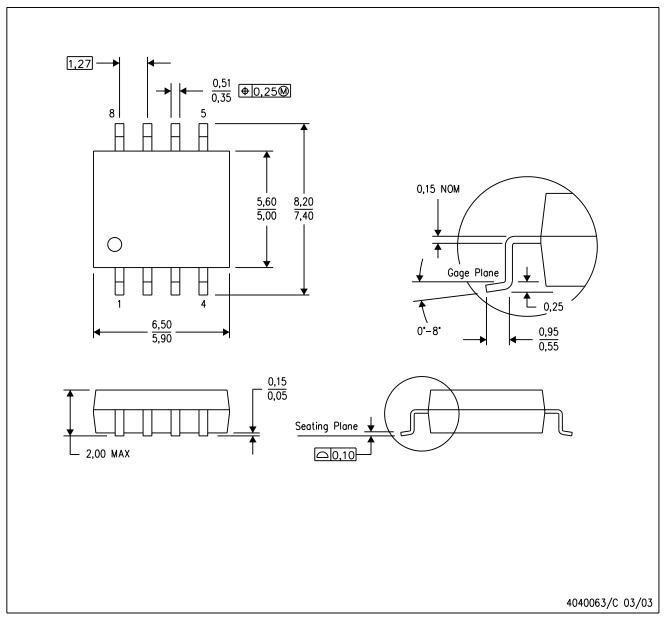
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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